



PCB Production Capability

NO	Project	2012	2013	2014
1	Products type	ELIC (4+2+4)、HDI、Flexible PCB、Rigid-flex PCB、Hi-frequency PCB、Metal based PCB、Multilayer PCB、Double-sided PCB、Backpanel	ELIC (4+2+4)、HDI、Flexible PCB、Rigid-flex PCB、Hi-frequency PCB、Metal based PCB、Multilayer PCB、Double-sided PCB、Backpanel	ELIC (4+2+4)、HDI、Flexible PCB、Rigid-flex PCB、Hi-frequency PCB、Metal based PCB、Multilayer PCB、Double-sided PCB、Backpanel
2	Common Base Material	Common FR4(common Tg)、Middle/High Tg0、LowDk/Df、Lead Free、Different ER、Material for high frequency、Ceramic material、Metal Material、CEM3、Halogen-Free	Common FR4(common Tg)、Middle/High Tg0、LowDk/Df、Lead Free、Different ER、Material for high frequency、Ceramic material、Metal Material、CEM3、Halogen-Free	Common FR4(common Tg)、Middle/High Tg0、LowDk/Df、Lead Free、Different ER、Material for high frequency、Ceramic material、Metal Material、CEM3、Halogen-Free
3	Finished Board Thickness	Min.0.05mm-1.5mm Core thickness 0.2mm-3.5mm	Min.0.05mm-1.5mm Core thickness 0.2mm-3.5mm	Min.0.05mm-1.5mm Core thickness 0.15mm-6.5mm
4	Copper Thickness	1/3OZ-5OZ	1/3OZ-6OZ	1/4OZ-12OZ
5	Max. Panel Size	800mm*610mm	800mm*610mm	≥4L: 1350mm*530mm
6	Min. Panel Size	2mm*10mm	2mm*10mm	2mm*10mm
7	Min. Drill Size	Laser hole 0.075mm/3mil, PTH 0.20mm/8mil	Laser hole 0.075mm/3mil, PTH 0.15mm/6mil	Laser hole 0.075mm/3mil, PTH 0.05mm/2mil
8	Min. Trace Width/Space	0.05mm/0.05mm (2mil/2mil)	0.05mm/0.05mm (2mil/2mil)	0.05mm/0.04mm (2mil/1.6mil)
9	SM Ink Type	Ordinary、Environmental protection、LDI Specialized ink	Ordinary、Environmental protection、LDI Specialized ink	Ordinary、Environmental protection、LDI Specialized ink
10	SM Ink Colour	Green,green full/halfdumb, yellow,blue, the other red, white,black	Green,green full/halfdumb, yellow,blue,the other red, white,black	Green,green full/halfdumb, yellow,blue, the other red, white,black
11	Layer registration	+/-0.05mm/2mil	+/-0.05mm/2mil	± 0.038mm/1.5mil
12	Outline Registration	+/-0.10mm/4mil	+/-0.075mm/3mil	± 0.038mm/1.5mil
13	Surface Finish	HAL、Immersion Gold Ni/Au、ENIG+OSP、OSP、Electroplated Gold、Immersion Tin、Immersion Silver	HAL、Immersion Gold Ni/Au、ENIG+OSP、OSP、Electroplated Gold、Immersion Tin、Immersion Silver	HAL、Immersion Gold Ni/Au、ENIG+OSP、OSP、Electroplated Gold、Immersion Tin、Immersion Silver
14	Min. BGA PAD and Tolerance	0.25mm; +/-10%	0.20mm; +/-10%	0.20mm; +/-10%
15	Aspect Ratio	PTH 8:1、Laser 0.75: 1	PTH 10:1、Laser 1: 1	PTH 15:1、Laser 1: 1
16	Bow and Twist	0.50%	0.50%	0.50%
17	Impedance Control Tolerance	+/-10%	+/-8%	± 5%
18	Layer Counts	1-14 Layers	1-20 Layers	1-32 Layers
19	Daily Production Capability	3000m ²	3200m ²	3500m ²
20	Delivery Time	Sample 2-5days, M/P 5-8days	Sample 2-5days, M/P 5-8days	Sample 2-5days, M/P 5-8days